



PRESS RELEASE

January 2024

IMAPS Device Packaging Conference and Workshop on Advanced Packaging for Medical Microelectronics to Co-locate

Both events to take place March 18-22, 2024 in Fountain Hills, Arizona

Device Packaging Conference 2024 (March 18-21)

The 20th Annual Device Packaging Conference (DPC 2024) will be held March 18-21, 2024, at the WeKoPa Resort and Conference Center in Fountain Hills, Arizona. This esteemed event brings together industry engineers, researchers and top experts involved in advanced packaging and microelectronics assembly with a multi-faceted technical program and unique networking events.

The technical content includes an unrivaled, concurrent 3-track program with 108 speakers and poster presentations covering topics related to Heterogeneous 2D & 3D Integration, Fan-Out, Wafer/Panel Level Packaging & Flip Chip, and Next Gen Applications.

Attendees will hear from five keynote speakers from AMD, Aptive, Auburn University, Facebook Reality Labs and Intel. An evening panel discussion is planned on *“Next Killer Application: Will Heterogeneous Integration be the Enabler?”* and a business plenary session will focus on *“How Geopolitics are Reshaping the Global Semiconductor Industry”*.

Attendees can also register for 12 Professional Development Courses. These focused courses provide a learning opportunity for looking to enhance their skills and knowledge, or those new to the industry.

A sold-out exhibit hall will showcase the latest products, technologies and applications. Registration includes networking opportunities that promote attendee interaction: welcome and exhibit hall receptions, group lunches, and a DEI Roundtable session. A post-conference golf scramble and guided hike will be offered to raise funds for the IMAPS Microelectronics Foundation and the 3D InCites DEI Fund, respectively.

In 2023, DPC welcomed a record number of participants and 2024 is expected to be record breaking once again.

Conference details and registration are available at <https://imaps.org/page/Device-Packaging>

Workshop on Advanced Packaging for Medical Microelectronics (March 21-22)

This advanced technology workshop brings together technologists in semiconductor packaging with life science experts interested in applying advanced packaging methods to enable the next generation of medical microelectronic devices. Attendees and exhibitors will be exposed to a wide variety of disciplines to encourage discussions involving technologies, products, strategies, current and emerging markets, and collaborations in areas such as Disease Detection, Materials, Assembly and Applications/Products. The two-day event will draw

invited experts in the fields of medicine, medical devices, biomaterials, microelectronics, semiconductor packaging, and product assembly.

Keynote speakers will include Bart Carey (CVRX), James Cavuoto (Neurotech Reports), Steve Hillerich (Samtec) and Rainer Platz (Valtronic).

A discount is available if attending both events.

To learn more about the workshop, visit: <https://imaps.org/page/medical>

About IMAPS

The International Microelectronics Assembly and Packaging Society is the largest society dedicated to the advancement and growth of microelectronics and electronics packaging. Worldwide, IMAPS offers educational and marketing opportunities for industry professionals, packaging organizations, and students through technical conferences and workshops, professional development courses, IMAPSource microelectronics packaging research library, local chapters and exhibitions. The Society encompasses a wide-range of technologies and topics critical to microelectronics assembly and packaging, including: on-shoring, heterogenous integration, fan-out wafer level packaging, 2.5D/3D technologies, system-in-package, photonics/optical, power packaging, CPI, package design/modeling, interconnects, wire bonding, flip chip, MEMS, sensors, packaging for 5g/6g, RF/wireless, signal/power integrity, advanced materials, substrates and more.

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